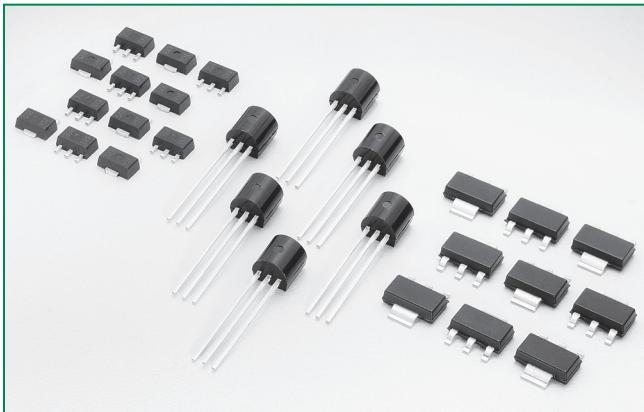


SxX8xSx Series



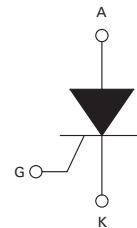
Description

New device series offers high static dv/dt and lower turn off (t_{qoff}) sensitive SCR with its small die planar construction design. It is specifically designed for GFCI (Ground Fault Circuit Interrupter) and Gas Ignition applications. All SCRs junctions are glass-passivated to ensure long term reliability and parametric stability.

Features

- RoHS compliant and Halogen-Free
- Improved turn-off time ($t_{qoff} < 25 \mu\text{sec}$)
- Thru-hole and surface mount packages
- Surge current capability > 10Amps
- Blocking voltage (V_{DRM} / V_{RRM}) capability - up to 800V
- Sensitive gate for direct microprocessor interface
- High dv/dt noise immunity

Schematic Symbol



Main Features

Symbol	Value	Unit
I_{TRMS}	0.8	A
V_{DRM} / V_{RRM}	400 to 800	V
I_{GT}	5 to 200	μA

Applications

The SxX8xSx EV series is specifically designed for GFCI (Ground Fault Circuit Interrupter) and gas ignition applications.

Absolute Maximum Ratings

Symbol	Parameter		Value	Unit
I_{TRMS}	RMS on-state current (full sine wave)	TO-92	$T_c = 55^\circ\text{C}$	0.8
		SOT-89	$T_c = 60^\circ\text{C}$	0.8
		SOT-223	$T_L = 60^\circ\text{C}$	0.8
I_{TAV}	Average on-state current	TO-92	$T_c = 55^\circ\text{C}$	0.51
		SOT-89	$T_c = 60^\circ\text{C}$	0.51
		SOT-223	$T_L = 60^\circ\text{C}$	0.51
I_{TSM}	Non repetitive surge peak on-state current (Single cycle, T_j initial = 25°C)	TO-92 SOT-89 SOT-223	F = 50Hz	8
			F = 60Hz	10
I^2t	I^2t Value for fusing	$t_p = 10 \text{ ms}$	F = 50 Hz	A^2s
		$t_p = 8.3 \text{ ms}$	F = 60 Hz	A^2s
di/dt	Critical rate of rise of on-state current $I_G = 10\text{mA}$	TO-92 SOT-89 SOT-223	$T_j = 125^\circ\text{C}$	50
				$\text{A}/\mu\text{s}$
I_{GM}	Peak Gate Current	$t_p = 10 \mu\text{s}$	$T_j = 125^\circ\text{C}$	1.0
$P_{G(AV)}$	Average gate power dissipation	—	$T_j = 125^\circ\text{C}$	0.1
T_{stg}	Storage junction temperature range	—	—	$-40 \text{ to } 150^\circ\text{C}$
T_j	Operating junction temperature range	—	—	$-40 \text{ to } 125^\circ\text{C}$

Electrical Characteristics ($T_J = 25^\circ\text{C}$, unless otherwise specified)

Symbol	Description	Test Conditions	Limit	Value			Unit
				SxX8yS1	SxX8yS2	SxX8yS	
I_{GT}	DC Gate Trigger Current	$V_D = 6\text{V}$ $R_L = 100 \Omega$	MIN.	0.5	1	15	µA
			MAX.	5	50	200	µA
V_{GT}	DC Gate Trigger Voltage	$V_D = 6\text{V}$ $R_L = 100 \Omega$	MAX.	0.8			V
V_{GRM}	Peak Reverse Gate Voltage	$I_{RG} = 10\mu\text{A}$	MIN.	5			V
I_H	Holding Current	$R_{GK} = 1 \text{ k}\Omega$ Initial Current = 20mA	MAX.	5			mA
(dv/dt)s	Critical Rate-of-Rise of Off-State Voltage	$T_J = 125^\circ\text{C}$ $V_D = V_{DRM} / V_{RRM}$ Exp. Waveform $R_{GK} = 1 \text{ k}\Omega$	MIN.	75			V/µs
V_{GD}	Gate Non-Trigger Voltage	$V_D = V_{DRM}$ $R_{GK} = 1 \text{ k}\Omega$ $T_J = 25^\circ\text{C}$	MIN.	0.2			V
t_q	Turn-Off Time	$T_J = 25^\circ\text{C} @ 600 \text{V}$ $R_{GK} = 1 \text{ k}\Omega$	MAX.	30	25	25	µs
t_{gt}	Turn-On Time	$I_G = 10\text{mA}$ $PW = 15\text{usec}$ $I_T = 1.6\text{A(pk)}$	TYP.	2.0	2.0	2.0	µs

Note: x = voltage, y = package

Static Characteristics ($T_J = 25^\circ\text{C}$, unless otherwise specified)

Symbol	Description	Test Conditions	Limit	Value	Unit
V_{TM}	Peak On-State Voltage	$I_{TM} = 1.6\text{A (pk)}$	MAX.	1.70	V
I_{DRM}	Off-State Current, Peak Repetitive	$T_J = 25^\circ\text{C} @ V_D = V_{DRM}$ $R_{GK} = 1 \text{ k}\Omega$	MAX.	3	µA
		$T_J = 125^\circ\text{C} @ VD = V_{DRM}$ $R_{GK} = 1 \text{ k}\Omega$	MAX.	500	µA

Thermal Resistances

Symbol	Description	Test Conditions	Value	Unit	
$R_{th(j-c)}$	Junction to case (AC)	$I_T = 0.8\text{A}_{(\text{RMS})}^1$	TO-92	75	°C/W
			SOT-223	30	°C/W
			SOT-89	50	°C/W
$R_{th(j-a)}$	Junction to ambient	$I_T = 0.8\text{A}_{(\text{RMS})}^1$	TO-92	150	°C/W
			SOT-223	60	°C/W
			SOT-89	90	°C/W

¹ 60Hz AC resistive load condition, 100% conduction.

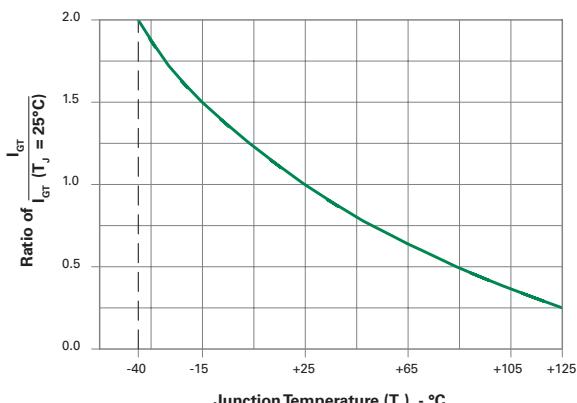
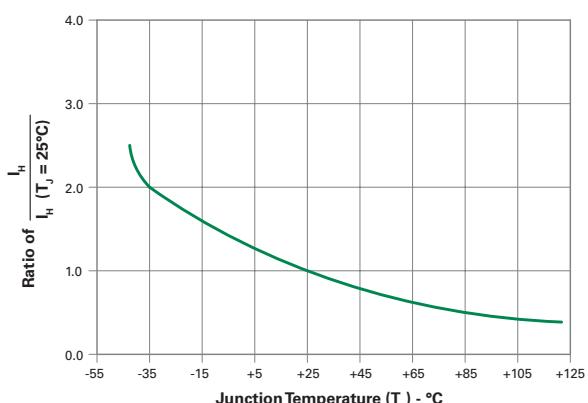
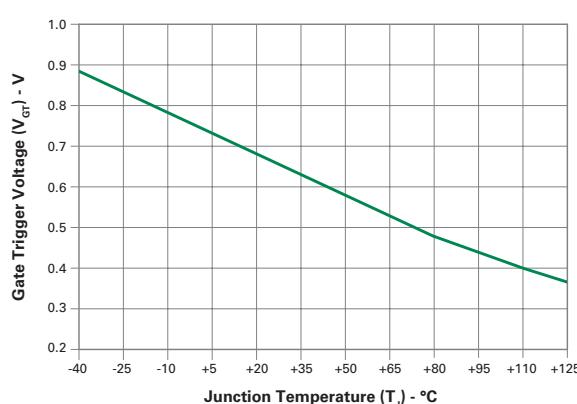
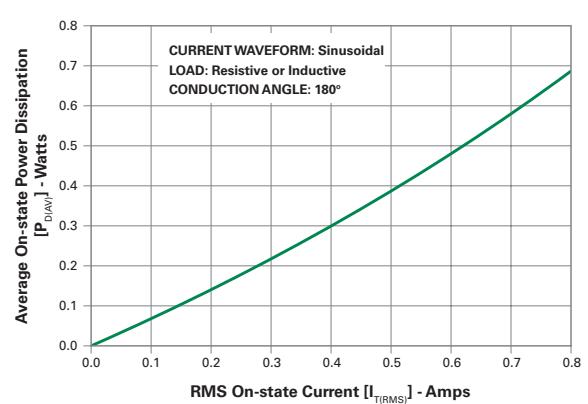
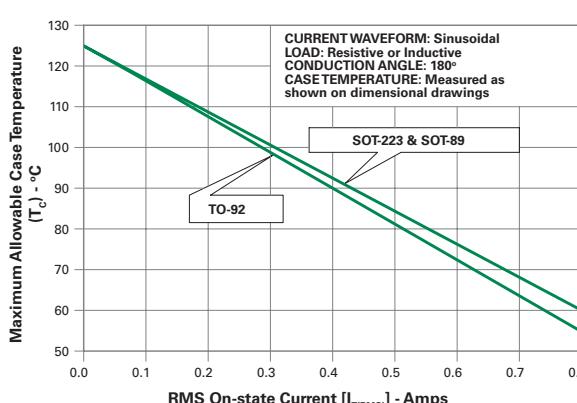
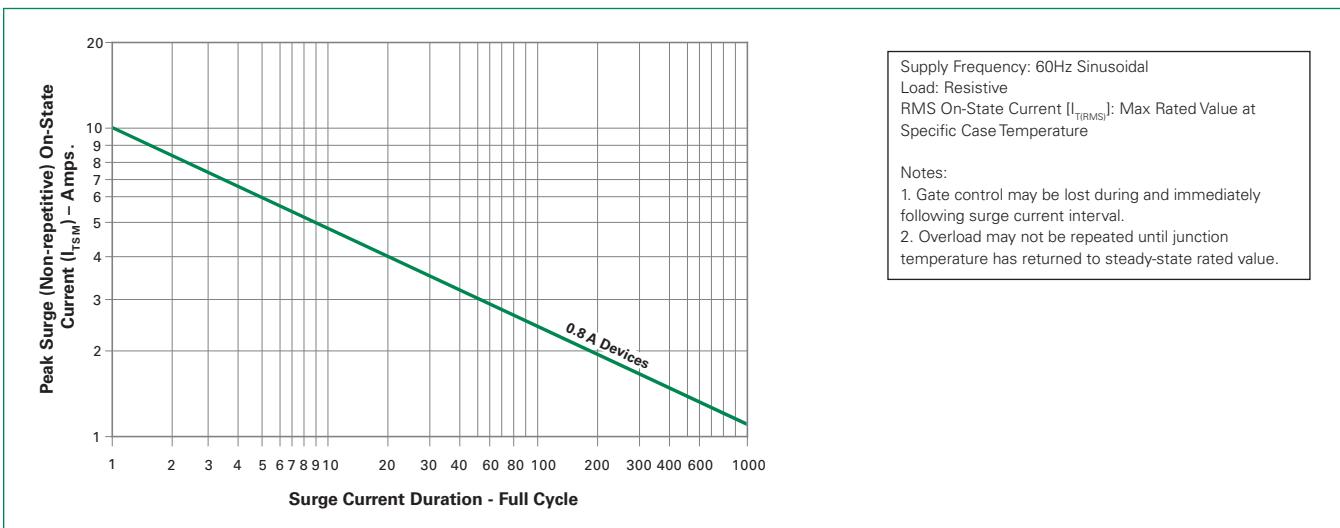
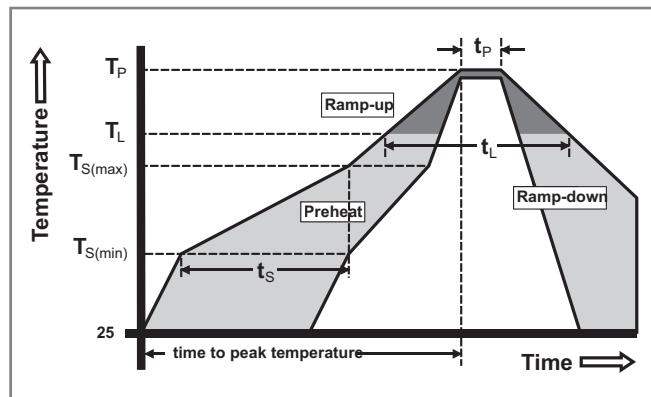
Figure 1: Normalized DC Gate Trigger Current For All Quadrants vs. Junction Temperature

Figure 2: Normalized DC Holding Current vs. Junction Temperature

Figure 3: Normalized DC Gate Trigger Voltage vs. Junction Temperature

Figure 4: Power Dissipation (Typical) vs. RMS On-State Current

Figure 5: Maximum Allowable Case Temperature vs. On-State Current


Figure 6: Surge Peak On-State Current vs. Number of Cycles


Soldering Parameters

Reflow Condition		Pb – Free assembly
Pre Heat	-Temperature Min ($T_{S(min)}$)	150°C
	-Temperature Max ($T_{S(max)}$)	200°C
	-Time (min to max) (t_s)	60 – 180 secs
Average ramp up rate (Liquidus Temp) (T_L) to peak		5°C/second max
Reflow	$T_{S(max)}$ to T_L - Ramp-up Rate	5°C/second max
	-Temperature (T_L) (Liquidus)	217°C
	-Time (min to max) (t_s)	60 – 150 seconds
Peak Temperature (T_p)		260 ^{+0/-5} °C
Time within 5°C of actual peak Temperature (t_p)		20 – 40 seconds
Ramp-down Rate		5°C/second max
Time 25°C to peak Temperature (T_p)		8 minutes Max.
Do not exceed		280°C



Physical Specifications

Terminal Finish	100% Matte Tin-plated.
Body Material	UL recognized epoxy meeting flammability classification 94V-0.
Lead Material	Copper Alloy

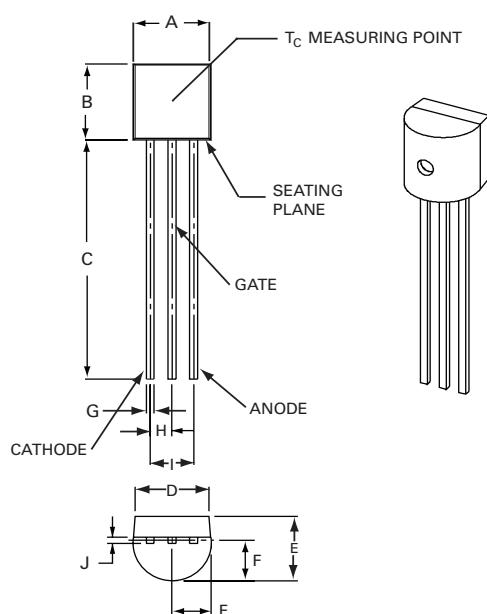
Design Considerations

Careful selection of the correct device for the application's operating parameters and environment will go a long way toward extending the operating life of the Thyristor. Good design practice should limit the maximum continuous current through the main terminals to 75% of the device rating. Other ways to ensure long life for a power discrete semiconductor are proper heat sinking and selection of voltage ratings for worst case conditions. Overheating, overvoltage (including dv/dt), and surge currents are the main killers of semiconductors. Correct mounting, soldering, and forming of the leads also help protect against component damage.

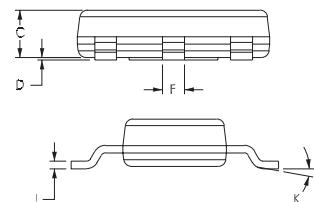
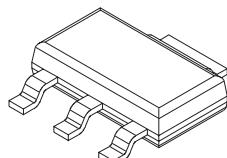
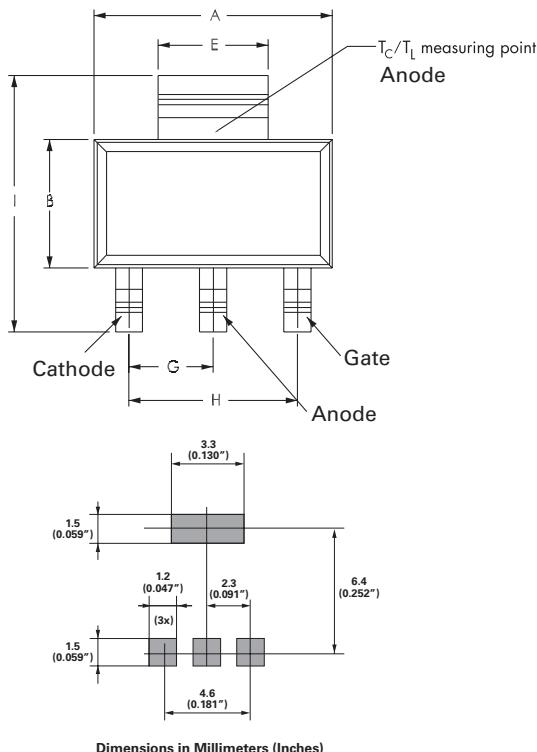
Reliability/Environmental Tests

Test	Specifications and Conditions
AC Blocking	MIL-STD-750, M-1040, Cond A Applied Peak AC voltage @ 110°C for 1008 hours
Temperature Cycling	MIL-STD-750, M-1051, 100 cycles; -40°C to +150°C; 15-min dwell-time
Temperature/Humidity	EIA / JEDEC, JESD22-A101 1008 hours; 320V - DC: 85°C; 85% rel humidity
High Temp Storage	MIL-STD-750, M-1031, 1008 hours; 150°C
Low-Temp Storage	1008 hours; -40°C
Thermal Shock	MIL-STD-750, M-1056 10 cycles; 0°C to 100°C; 5-min dwell-time at each temperature; 10 sec (max) transfer time between temperature
Autoclave	EIA / JEDEC, JESD22-A102 168 hours (121°C at 2 ATMs) and 100% R/H
Resistance to Solder Heat	MIL-STD-750 Method 2031
Solderability	ANSI/J-STD-002, category 3, Test A
Lead Bend	MIL-STD-750, M-2036 Cond E

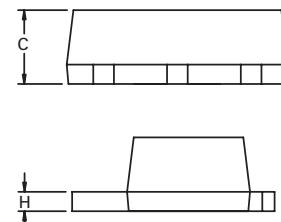
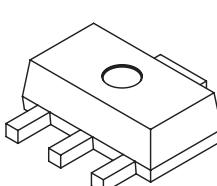
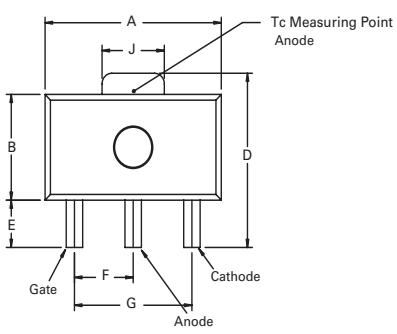
Dimensions – TO-92



Dimension	Inches		Millimeters	
	Min	Max	Min	Max
A	0.175	0.205	4.450	5.200
B	0.170	0.210	4.320	5.330
C	0.500		12.70	
D	0.135		3.430	
E	0.125	0.165	3.180	4.190
F	0.080	0.105	2.040	2.660
G	0.016	0.021	0.407	0.533
H	0.045	0.055	1.150	1.390
I	0.095	0.105	2.420	2.660
J	0.015	0.020	0.380	0.500

Dimensions – SOT-223


Dimensions	Inches			Millimeters		
	Min	Typ	Max	Min	Typ	Max
A	0.248	0.256	0.264	6.30	6.50	6.70
B	0.130	0.138	0.146	3.30	3.50	3.70
C	—	—	0.071	—	—	1.80
D	0.001	—	0.004	0.02	—	0.10
E	0.114	0.118	0.124	2.90	3.00	3.15
F	0.024	0.027	0.034	0.60	0.70	0.85
G	—	0.090	—	—	2.30	—
H	—	0.181	—	—	4.60	—
I	0.264	0.276	0.287	6.70	7.00	7.30
J	0.009	0.010	0.014	0.24	0.26	0.35
K	10° MAX					

Dimensions – SOT-89


Dimension	Inches			Millimeters		
	Min	Typ	Max	Min	Typ	Max
A	0.173	—	0.181	4.40	—	4.60
B	0.090	—	0.102	2.29	—	2.60
C	0.055	—	0.063	1.40	—	1.60
D	0.155	—	0.167	3.94	—	4.25
E	0.035	—	0.047	0.89	—	1.20
F	0.056	—	0.062	1.42	—	1.57
G	0.115	—	0.121	2.92	—	3.07
H	0.014	—	0.017	0.35	—	0.44
I	0.014	—	0.019	0.36	—	0.48
J	0.064	—	0.072	1.62	—	1.83

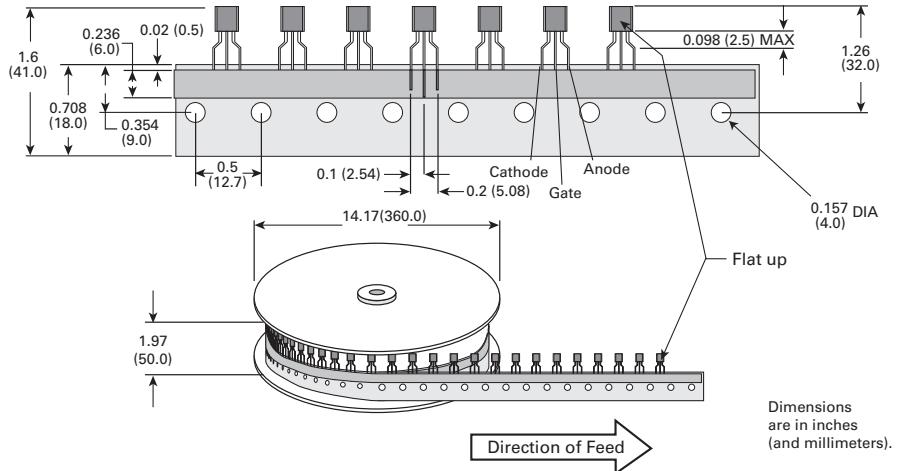
Product Selector

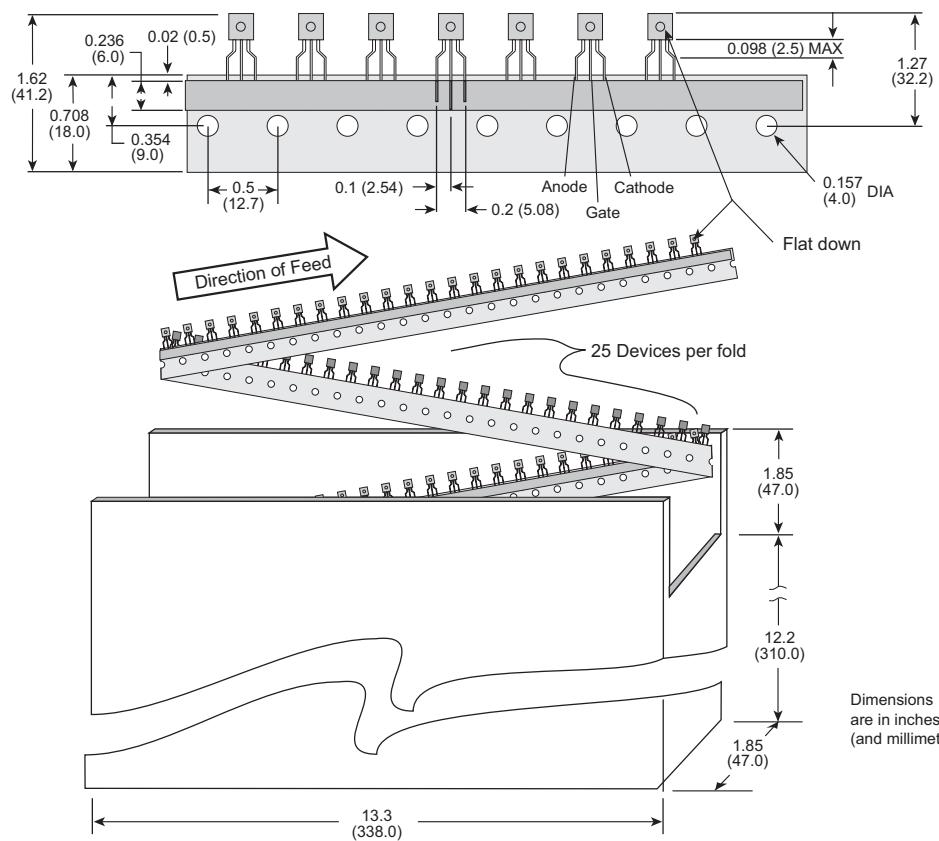
Part Number	Voltage			Gate Sensitivity	Package
	400V	600V	800V		
S4X8ES	X	—	—	200 µA	TO-92
S6X8ES	—	X	—	200 µA	TO-92
S8X8ES	—	—	X	200 µA	TO-92
S4X8TS	X	—	—	200 µA	SOT-223
S6X8TS	—	X	—	200 µA	SOT-223
S8X8TS	—	—	X	200 µA	SOT-223
S4X8BS	X	—	—	200 µA	SOT-89
S6X8BS	—	X	—	200 µA	SOT-89
S4X8ES1	X	—	—	5 µA	TO-92
S6X8ES1	—	X	—	5 µA	TO-92
S8X8ES1	—	—	X	5 µA	TO-92
S4X8TS1	X	—	—	5 µA	SOT-223
S6X8TS1	—	X	—	5 µA	SOT-223
S8X8TS1	—	—	X	5 µA	SOT-223
S4X8ES2	X	—	—	50 µA	TO-92
S6X8ES2	—	X	—	50 µA	TO-92
S8X8ES2	—	—	X	50 µA	TO-92
S4X8TS2	X	—	—	50 µA	SOT-223
S6X8TS2	—	X	—	50 µA	SOT-223
S8X8TS2	—	—	X	50 µA	SOT-223

Packing Options

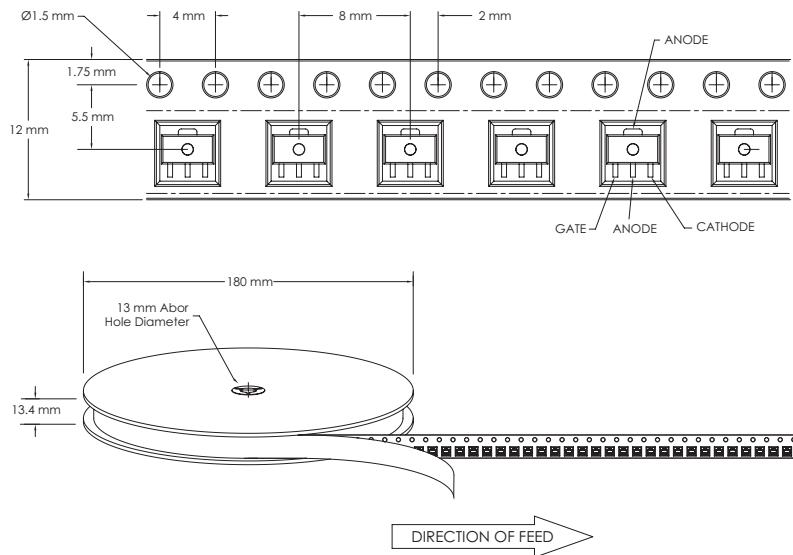
Part Number	Marking	Weight	Packing Mode	Base Quantity
SxX8ESy	SxX8ESy	0.170g	Bulk	2500
SxX8ESyAP	SxX8ESy	0.170g	Ammo Pack	2000
SxX8ESyRP	SxX8ESy	0.170g	Tape & Reel	2000
SxX8TSyRP	SxX8TSy	0.120g	Tape & Reel	1000
SxX8BSRP	xX8	0.053g	Tape & Reel	1000
SxX8BSRP1	xX8	0.053g	Tape & Reel	1000

Note: x = voltage, y = gate sensitivity

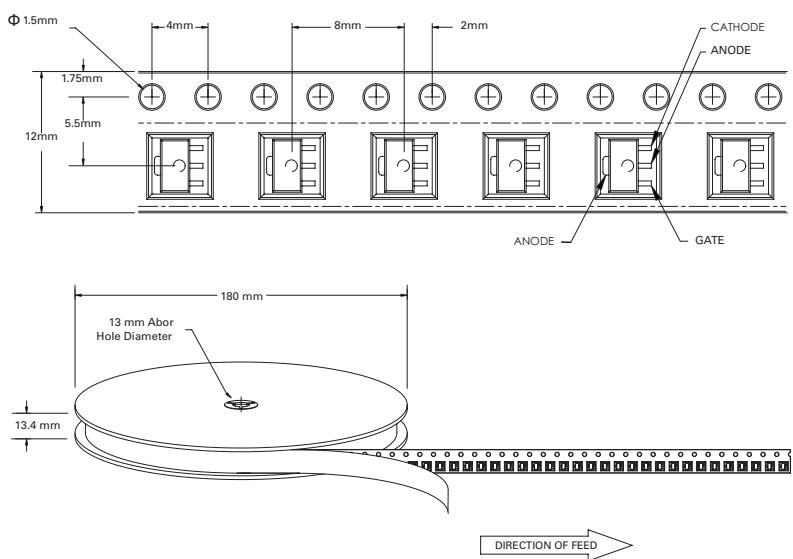
TO-92 (3-lead) Reel Pack (RP) Radial Leaded Specifications
Meets all EIA-468-C Standards

 Dimensions
are in inches
(and millimeters).

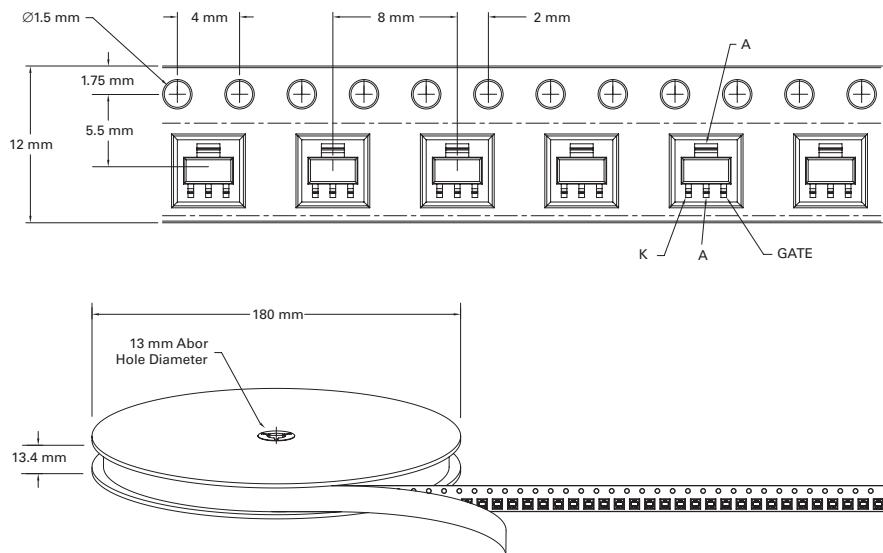
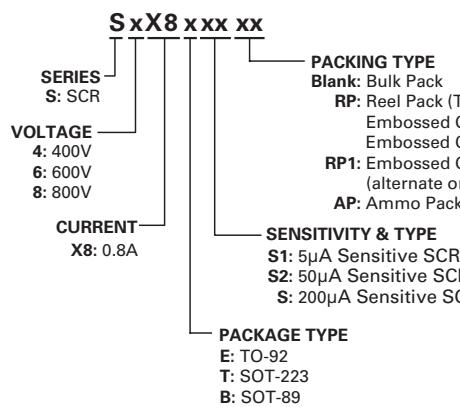
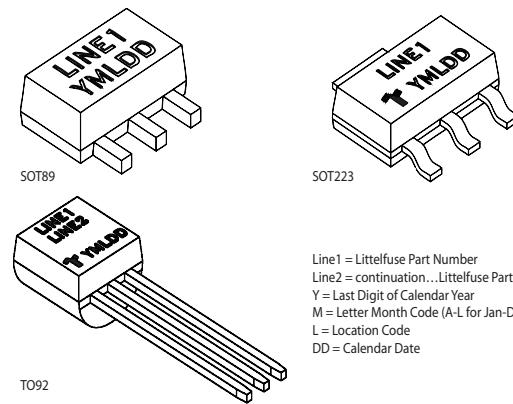
TO-92 (3-lead) Ammo Pack (AP) Radial Leaded Specifications
Meets all EIA-468-C Standards

 Dimensions
are in inches
(and millimeters).

SOT-89 Reel Pack (RP) Specifications



SOT-89 Reel Pack (RP1) Specifications



SOT-223 Reel Pack (RP) Specifications

Part Numbering System

Part Marking System




OCEAN CHIPS

Океан Электроники

Поставка электронных компонентов

Компания «Океан Электроники» предлагает заключение долгосрочных отношений при поставках импортных электронных компонентов на взаимовыгодных условиях!

Наши преимущества:

- Поставка оригинальных импортных электронных компонентов напрямую с производств Америки, Европы и Азии, а так же с крупнейших складов мира;
- Широкая линейка поставок активных и пассивных импортных электронных компонентов (более 30 млн. наименований);
- Поставка сложных, дефицитных, либо снятых с производства позиций;
- Оперативные сроки поставки под заказ (от 5 рабочих дней);
- Экспресс доставка в любую точку России;
- Помощь Конструкторского Отдела и консультации квалифицированных инженеров;
- Техническая поддержка проекта, помощь в подборе аналогов, поставка прототипов;
- Поставка электронных компонентов под контролем ВП;
- Система менеджмента качества сертифицирована по Международному стандарту ISO 9001;
- При необходимости вся продукция военного и аэрокосмического назначения проходит испытания и сертификацию в лаборатории (по согласованию с заказчиком);
- Поставка специализированных компонентов военного и аэрокосмического уровня качества (Xilinx, Altera, Analog Devices, Intersil, Interpoint, Microsemi, Actel, Aeroflex, Peregrine, VPT, Syfer, Eurofarad, Texas Instruments, MS Kennedy, Miteq, Cobham, E2V, MA-COM, Hittite, Mini-Circuits, General Dynamics и др.);

Компания «Океан Электроники» является официальным дистрибутором и эксклюзивным представителем в России одного из крупнейших производителей разъемов военного и аэрокосмического назначения «JONHON», а так же официальным дистрибутором и эксклюзивным представителем в России производителя высокотехнологичных и надежных решений для передачи СВЧ сигналов «FORSTAR».



JONHON

«JONHON» (основан в 1970 г.)

Разъемы специального, военного и аэрокосмического назначения:

(Применяются в военной, авиационной, аэрокосмической, морской, железнодорожной, горно- и нефтедобывающей отраслях промышленности)

«FORSTAR» (основан в 1998 г.)

ВЧ соединители, коаксиальные кабели, кабельные сборки и микроволновые компоненты:

(Применяются в телекоммуникациях гражданского и специального назначения, в средствах связи, РЛС, а так же военной, авиационной и аэрокосмической отраслях промышленности).



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